

In the Claims:

Claims 1 to 11 (canceled).

1 12. (new) A method for producing a circuit arrangement having  
2 a carrier body with circuit components secured to an upper  
3 side (12) of said carrier body having thermal lead-through  
4 vias (7) passing through said carrier body (5) from said  
5 upper side (12) to an underside (13) of said carrier body,  
6 said method comprising the following steps:

7 a) first applying a first metallization base layer (6) to  
8 said carrier body (5) and to said thermal lead-through  
9 vias (7),

10 b) screen printing a viscous material (8) into said  
11 thermal lead-through vias (7) thereby closing said  
12 thermal lead-through vias (7) to prevent solder of a  
13 following soldering step from passing through said  
14 thermal lead-through vias,

15 c) removing, following curing of said viscous material,  
16 any excess of said viscous material (8) from said  
17 underside (13) of said carrier body (5), and

18 d) second applying at least one further metallization  
19 layer (17) to said first metallization base layer (6)  
20 outside said viscous material on the inside of said  
21 thermal lead-through vias, on the upper side and on  
22 the underside of said carrier body.

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1 13. (new) The method of claim 12, wherein said second applying  
2 step is performed outside said viscous material (8)  
3 covering a portion of said first metallization base layer  
4 in said lead-through vias (7).

1 14. (new) The method of claim 12, wherein said removing step is  
2 performed as a mechanical cleaning process.

1 15. (new) The method of claim 14, wherein said mechanical  
2 cleaning process is performed as a mechanical brush  
3 grinding step.

1 16. (new) The method of claim 12, wherein said removing step is  
2 performed as a chemical cleaning process.

1 17. (new) The method of claim 12, further comprising, following  
2 said second applying step, a step of attaching said circuit  
3 components (1) to said upper side (12) by a reflow  
4 soldering process.

1 18. (new) The method of claim 12, further comprising, following  
2 said second applying step, a step of applying a thermally  
3 conducting, electrically insulating film (9) to said  
4 underside (13) of said carrier body.

1 19. (new) The method of claim 18, further comprising connecting  
2 said thermally conducting, electrically insulating film to  
3 a cooling body.

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1     **20.**   (new) The method of claim 12, further comprising using as  
2           said viscous material a solid epoxy material which is  
3           sufficiently viscous for performing said screen printing  
4           step.

1     **21.**   (new) The method of claim 12, further comprising performing  
2           said step of screen printing on said underside (13) of said  
3           carrier body.

1     **22.**   (new) The method of claim 12, wherein said second applying  
2           step is performed by applying a nickel-gold coating to said  
3           first metallization base layer outside said viscous  
4           material, to form said second metallization layer (17).

**[RESPONSE CONTINUES ON NEXT PAGE]**

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